



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10352	REV: C	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 6/27/2017 4:32:14 PM	TEXAS INSTRUMENTS	

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